

Amendments to the Claims

This listing of claims will replace all prior listings of claims in the application.

Listing of Claims

1.-16. (Canceled)

17. (Canceled)

18. (Currently Amended) The plated resin molded article according to ~~claim 17~~claim 30, wherein ~~the~~ (A) matrix resin that has a saturated water absorption of at least 0.6% is selected from ~~a~~ polyamide-based resins, acrylate salt based resins, cellulosic resins, polyvinyl alcohol based resins and ~~polyether based resins~~resin.

19. (Currently Amended) The plated resin molded article according to ~~claim 17~~claim 30, wherein the surfactant comprises an emulsifying agent that is used in emulsion polymerization.

20. (Currently Amended) The plated resin molded article according to ~~claim 17~~claim 30, wherein the maximum value of the adhesive strength, according to JIS H8630, between the thermoplastic resin molded article and the metal plating layer is at least 10 kPa.

21. (Currently Amended) The plated resin molded article according to ~~claim 17~~claim 30, applied as an automotive component.

22. (Currently Amended) A method of producing a plated resin molded article according to ~~claim 17~~claim 30, wherein the plated resin molded article is produced by plating metal

on the surface of the thermoplastic resin molded article, the method comprising the step of contact-treating the thermoplastic resin molded article with an acid or base that does not contain a heavy metal, as a treatment preceding a metal plating step, and wherein a step of etching with a heavy metal-containing acid is not included.

23. (Previously Presented) The method of producing a plated resin molded article according to claim 22, comprising the steps of:

removing fat of the thermoplastic resin molded article; contact-treating the thermoplastic resin molded article with an acid or base that does not contain heavy metal; and a plating step, wherein the method does not include a step of etching with a heavy metal-containing acid.

24. (Previously Presented) The method of producing a plated resin molded article according to claim 22, comprising the steps of:

removing fat of the plastic resin molded article; contact-treating the thermoplastic resin molded article with an acid or base that does not contain a heavy metal; treating the thermoplastic resin molded article with a catalyst-imparting liquid; and a plating step, wherein the method does not include a step of etching with a heavy metal-containing acid.

25. (Previously Presented) The method of producing a plated resin molded article according to claim 22, wherein the concentration of the acid or base used in the step of contact-treating with an acid or base that does not contain a heavy metal is less than 4 normal.

26. (Previously Presented) The method of producing a plated resin molded article according to claim 22, wherein the step of contact-treating with an acid or base that does not contain a heavy metal is a step of immersing the thermoplastic

resin molded article in acid or base that does not contain heavy metal.

27. (Previously Presented) The method of producing a plated resin molded article according to claim 22, wherein the step of contact treating with an acid or base that does not contain a heavy metal is a step of immersing the thermoplastic resin molded article for 20 to 0.5 minutes at a liquid temperature of 10 to 80°C in an acid or base that does not contain a heavy metal.

28. (Previously Presented) The method of producing a plated resin molded article according to claim 22, wherein the acid that does not contain a heavy metal is selected from hydrochloric acid, phosphoric acid, sulfuric acid and organic acids.

29. (Previously Presented) The method of producing a plated resin molded article according to claim 22, wherein the base that does not contain a heavy metal is selected from hydroxides of an alkali metal or alkali earth metal.

30. (New) A plated resin molded article that has a metal plating layer provided on the surface of a thermoplastic resin molded article formed from a composition comprising the following components:

(A) 10 to 90 mass % of a matrix resin that has a water absorption after 24 hours in 23°C water, according to ISO62, of at least 0.6%;

(B) 90 to 10 mass % of a polyphenylene ether-based resin; and

(C) a water-soluble substance having a solubility at 25°C of not more than 300g in 100g of water and selected from the group of pentaerythritol and dipentaerythritol in an amount of 0.01 to 50 mass parts per 100 mass parts of the sum of components (A) and (B).

31. (New) A plated resin molded article that has a metal plating layer provided on the surface of a thermoplastic resin article formed from a composition comprising the following components:

(A) 10 to 90 mass % of a matrix resin that has a water absorption after 24 hours in 23°C water, according to ISO62, of at least 0.6%;

(B) 90 to 10 mass % of a polyphenylene ether-based resin;

(C) a water-soluble substance having a solubility at 25°C of not more than 300g in 100g of water and selected from the group consisting of pentaerythritol and dipentaerythritol in an amount of 0.01 to 50 mass parts per 100 mass parts of the sum of components (A) and (B); and at least one member selected from the group consisting of

(D) at least one of a surfactant and a coagulant in an amount of 0.01 to 10 mass parts per 100 mass parts of the sum of components (A) and (B); and

(E) a phosphorus compound in an amount of 0.1 to 30 mass parts per 100 mass parts of the sum of components (A) and (B).

32. (New) The plated resin molded article according to Claim 30, wherein the water-soluble substance (C) is present in an amount of from 0.01 to 15 mass parts per 100 mass parts of the sum of components (A) and (B).

33. (New) The plated resin molded article according to Claim 31, wherein the water-soluble substance (C) is present in an amount of from 0.01 to 10 mass parts per 100 mass parts of the sum of components (A) and (B) and a surfactant (D) is present in an amount of from 0.01 to 10 mass parts per 100 mass parts of the sum of components (A) and (B).

34. (New) The plated resin molded article according to Claim 33, additionally comprising a phosphorus compound (E) in

an amount of 0.1 to 10 mass parts per 100 mass parts of the sum of components (A)+(B).

35. (New) The plated resin molded article according to Claim 32, wherein component (A) is polyamide 6, component (B) is poly(2,6-dimethyl-1,4-phenylene ether) and component (C) is dipentaerythritol.

36. (New) The plated resin molded article according to Claim 33, wherein component (A) is polyamide 6, component (B) is poly(2,6-dimethyl-1,4-phenylene ether), component (C) is dipentaerythritol and component (D) is an α -olefin sulfonate.

37. (New) The plated resin molded article according to Claim 34, wherein component (A) is polyamide 6, component (B) is poly(2,6-dimethyl-1,4-phenylene ether), component (C) is dipentaerythritol, component (D) is an α -olefin sulfonate and component (E) is triphenyl phosphate.